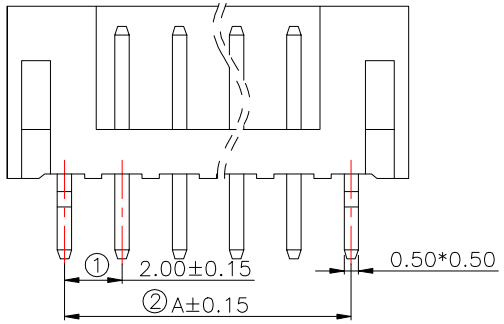
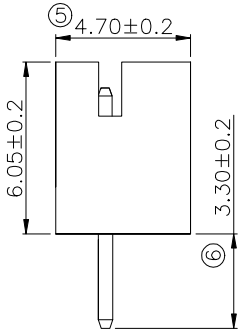
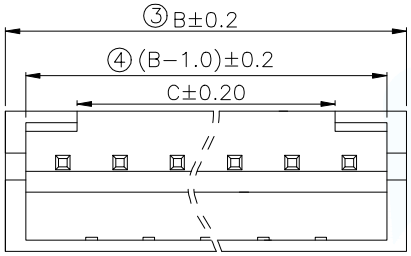
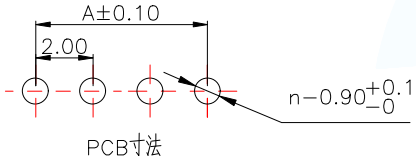
ROHS Compliant

MAPX	MODIFICATION	DATE	DRAW	APPROVE

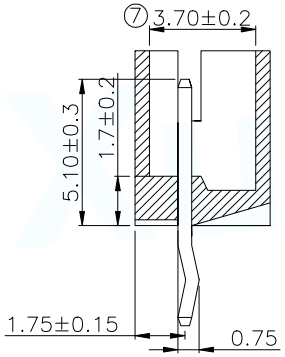




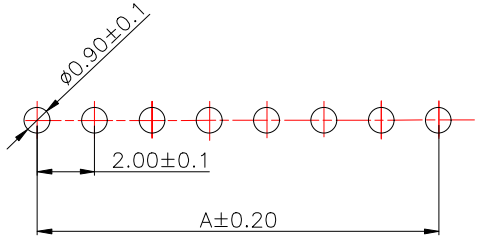




PCB寸法



Part No	Pin	A	B
WAFER−PH2.0−2PZZ	2	2.00	6.00
WAFER−PH2.0−3PZZ	3	4.00	8.00
WAFER−PH2.0−4PZZ	4	6.00	10.00
WAFER−PH2.0−5PZZ	5	8.00	12.00
WAFER−PH2.0−6PZZ	6	10.00	14.00
WAFER−PH2.0−7PZZ	7	12.00	16.00
WAFER−PH2.0−8PZZ	8	14.00	18.00
WAFER−PH2.0−9PZZ	9	16.00	20.00
WAFER−PH2.0−10PZZ	10	18.00	22.00
WAFER−PH2.0−11PZZ	11	20.00	24.00
WAFER−PH2.0−12PZZ	12	22.00	26.00
WAFER−PH2.0−13PZZ	13	24.00	28.00
WAFER−PH2.0−14PZZ	14	26.00	30.00
WAFER−PH2.0−15PZZ	15	28.00	32.00
WAFER−PH2.0−16PZZ	16	30.00	34.00
WAFER−PH2.0−17PZZ	17	32.00	36.00
WAFER−PH2.0−18PZZ	18	34.00	38.00
WAFER−PH2.0−19PZZ	19	36.00	40.00
WAFER−PH2.0−20PZZ	20	38.00	42.00



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

技术要求:
1.塑件材料:PA66(UL−94V−0)
2.接触件:黄铜镀锡
3.接触电阻:≤10mΩ
4.绝缘电阻:≥100MΩ
5.额定电压:250V AC DC
6.额定电流:2.0A AC DC
7.耐压:能承受1000V AC/Minute
8.工作温度:−25°~+85°
9.可焊性试验:浸锡面积≥95%温度235±5°,时间2.5±0.5秒
10.铅和镉等六大有害物质含量要符合环保要求.

序号	名称	材料	数量	备注
2	端子Contact	黄铜	N*1	电镀(锡):整个表面镀底镍30u"MIN,再镀锡80u"MIN
1	基座Wafer	PA66(UL94 V−0)	1	白色

MANUFACTURE DWG

东莞市讯普电子科技有限公司
DongGuan XunPu Electronics Co,Ltd

UNLESS OTHERWISE SPECIFED TOLERANCES

DECIMALS:	ANGLES:
.X±0.20	±2°
.XX±0.10	
.XXX±0.05	

CUSTOMER COPY

TITLE: WAFER PH2.0MM 直针

PAR	WAFER−PH2.0−NPZZ
DWN	
CHKD	
APVD	
SCALE1:1	UNIT:MM
SIZE:A4	SHEET:1F1
REV:A	

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XUNPU:

PHB2.0-02-20PZZ HDMI-212L DC-031A-A100 FPC-1.0AX-4PWCR-H25 FPC-1.0HF-4PWAR-H20
WAFER-PH2.0-3PWB WAFER-VH3.96-4PLB FPC-0.5AL-6PB FPC-0.5AX-30PWCR-H20
FPC-1.0AX-14PWCR-H25 TYPEC-304YDSW-ACP16 WAFER-GH1.25-6PLB WAFER-PH2.0-8PLB
FPC-0.5AS-5PWCR-H20 FPC-0.5FX-16PWCR-H20 RJ45-005-014-11 WAFER-MX1.25B-8PWB
FPC-0.5AX-24PWCR-H20 FPC-0.5FX-4PWCR-H20 FPC-0.5HF-10PWBR-H20 MU-103-ARW64
WAFER-PH2.0-11PZZ FPC-0.5FX-4PWBH15 WAFER-WBM4.2-16PJK-GB WAFER-XH2.54-4PWZ-H62
FPC-0.5FX-14PWCR-H20 SMA-KWE-323C-H13X23-LW WAFER-PH2.0-2PJK WAFER-PH2.0-6PWB
FPC-0.5FX-20PWBH15